

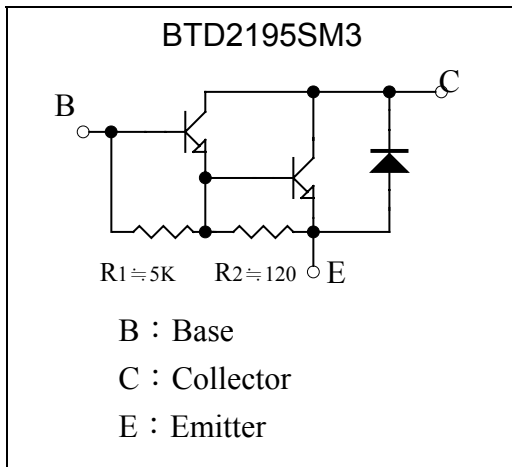
NPN Epitaxial Planar Transistor

BTD2195SM3

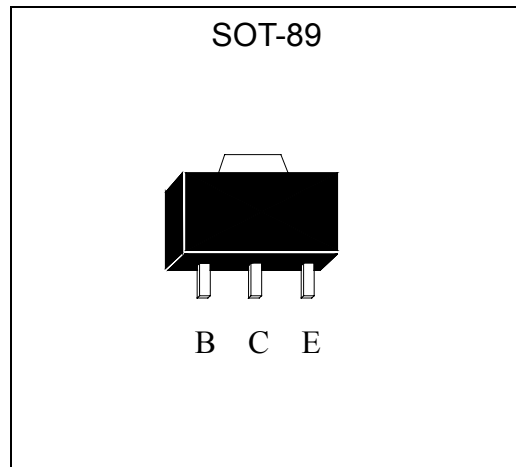
Description

The BTD2195SM3 is designed for use in general purpose amplifier and low speed switching application. Pb-free lead plating package process is adopted.

Equivalent Circuit

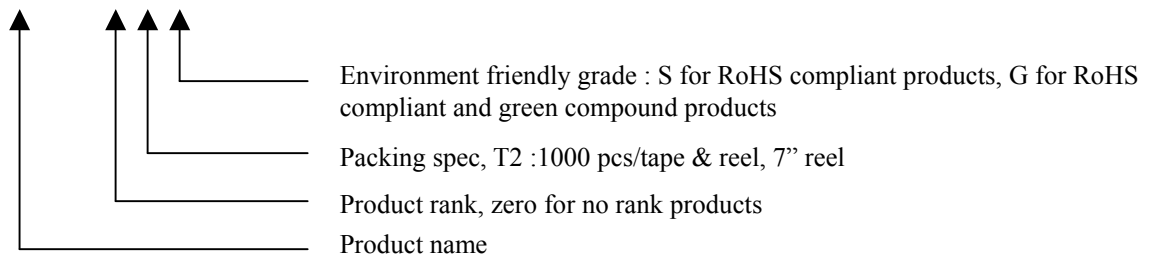


Outline



Ordering Information

Device	Package	Shipping
BTD2195SM3-0-T2-G	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / Tape & Reel





Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CBO}	150	V
Collector-Emitter Voltage	V _{CEO}	150	
Emitter-Base Voltage	V _{EBO}	5	
Collector Current (DC)	I _C	4	A
Collector Current (Pulse)	I _{CP}	6 (Note 1)	
Thermal Resistance, Junction to Ambient	R _{θJA}	208	°C/W
		125 (Note 2)	
		62.5 (Note 3)	
		85 (Note 4)	
Thermal Resistance, Junction to Case	R _{θJC}	43	
Power Dissipation	P _D	0.7	W
		1.2 (Note 2)	
		2.5 (Note 3)	
Power Dissipation @ T _C =25°C		3.5	
Operating Junction Temperature Range	T _j	-55~+175	°C
Storage Temperature Range	T _{stg}	-55~+175	

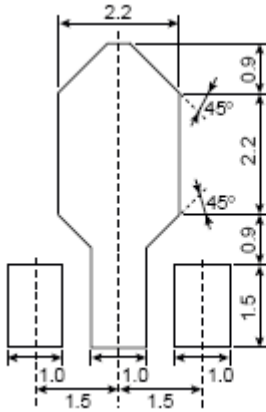
- Note : 1. Single Pulse P_w ≤ 350μs, Duty ≤ 2%.
 2. When mounted on a FR-4 PCB with area measuring 10×10×1 mm.
 3. When mounted on a ceramic board with area measuring 40×40×1mm.
 4. When mounted on a FR-4 PCB with area measuring 30×30×1 mm.

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CBO}	150	-	-	V	I _C =100μA, I _E =0
I _{CBO}	-	-	100	nA	V _{CB} =150V, I _E =0
I _{CEO}	-	-	1	μA	V _{CE} =150V, I _B =0
I _{EBO}	-	-	2	mA	V _{EB} =5V, I _C =0
*V _{CE(sat)}	-	-	1.2	V	I _C =2A, I _B =2mA
*V _{BE(on)}			2.2	V	V _{CE} =4V, I _C =2A
*h _{FE1}	2000	-	-	-	V _{CE} =4V, I _C =1A
*h _{FE2}	1000	-	-	-	V _{CE} =4V, I _C =2A
Cob	-		200	pF	V _{CB} =10V, I _E =0A, f=1MHz

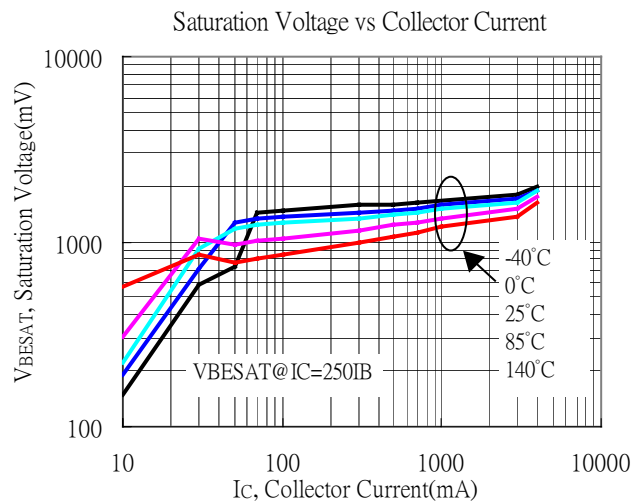
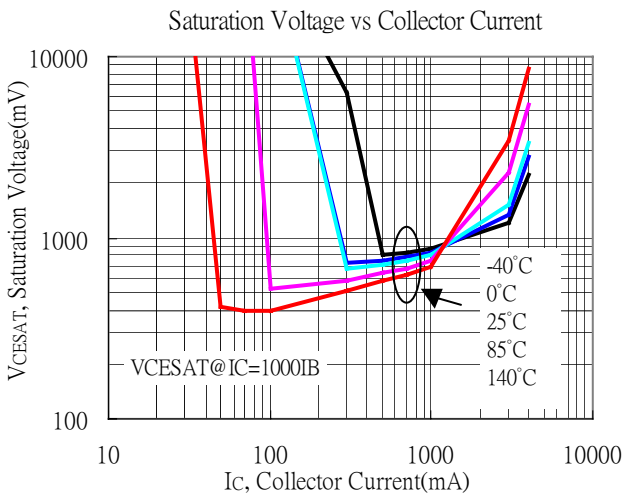
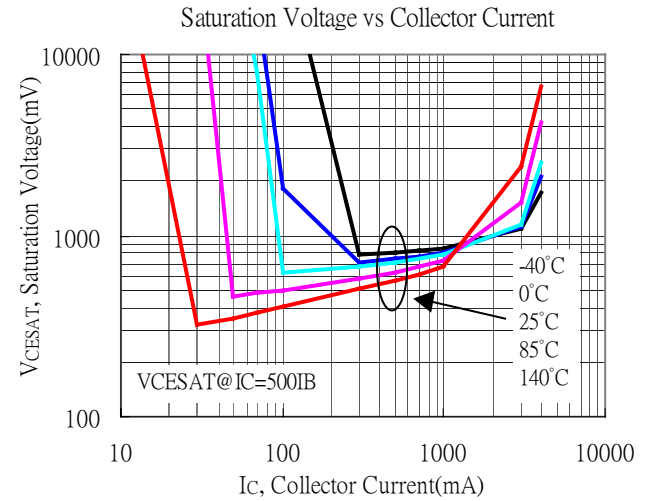
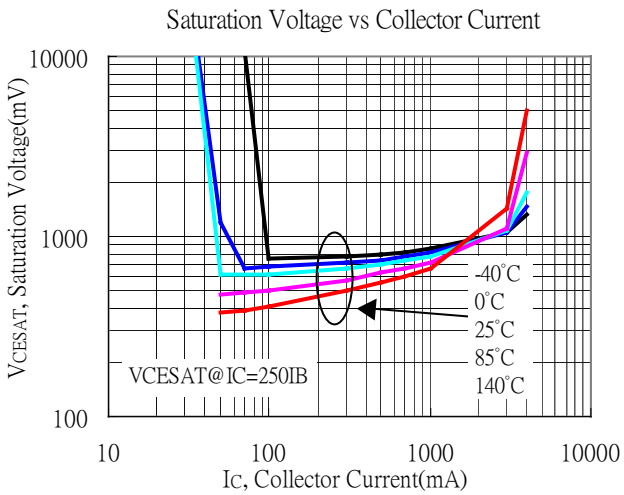
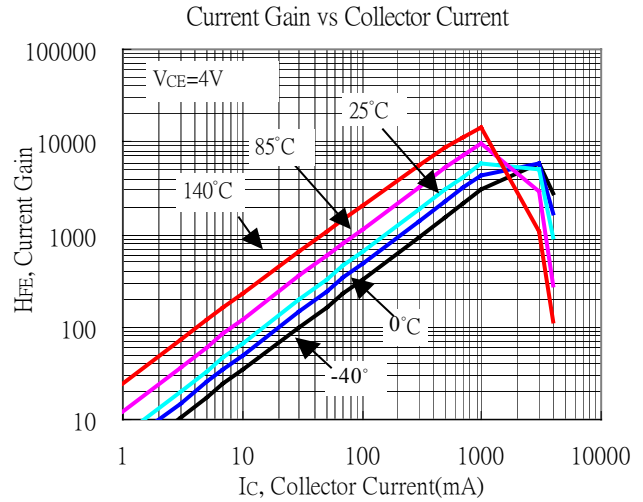
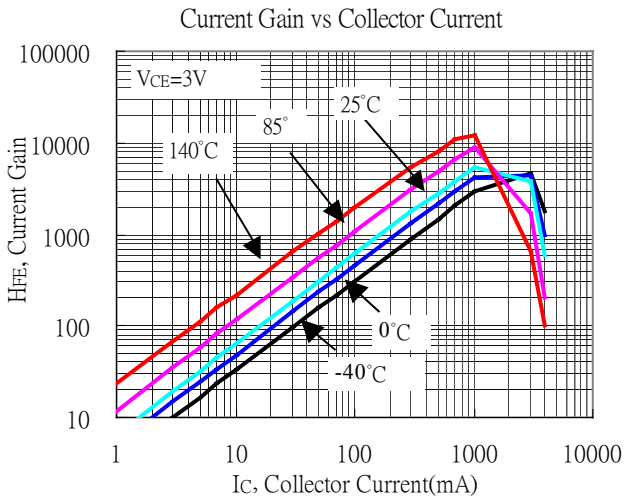
*Pulse Test : Pulse Width ≤ 380μs, Duty Cycles ≤ 2%

Recommended soldering footprint



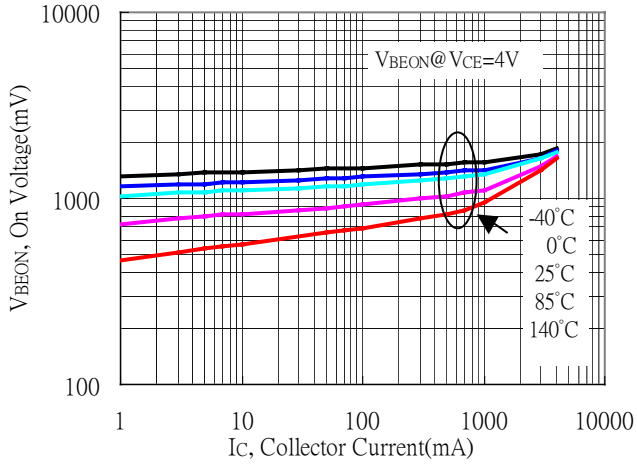
unit : mm

Typical Characteristics

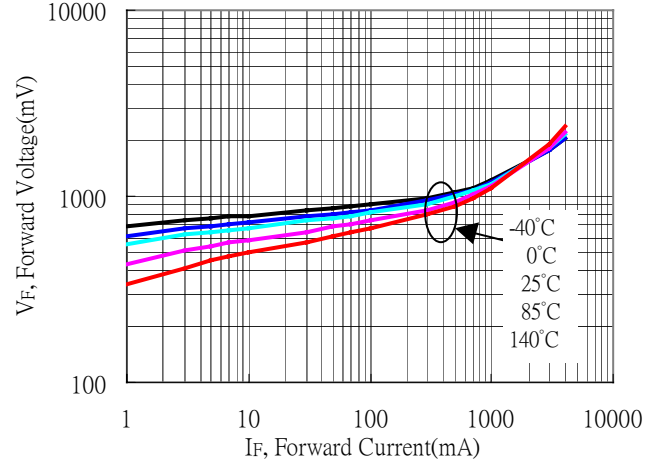


Typical Characteristics(Cont.)

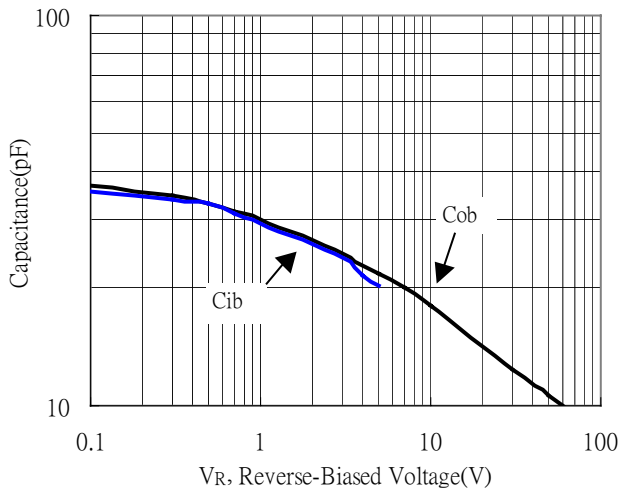
On Voltage vs Collector Current



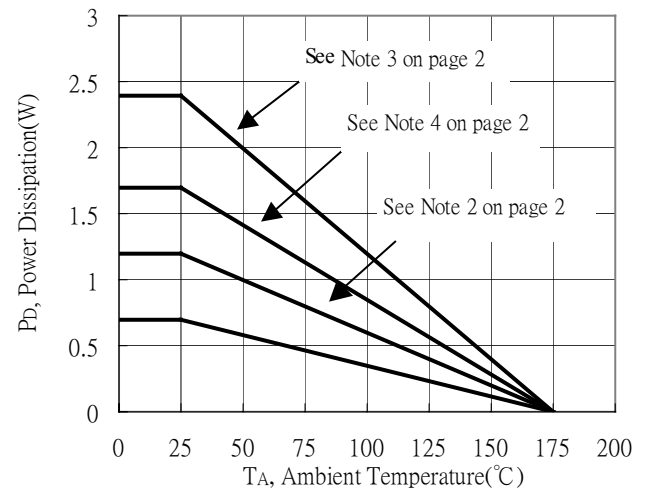
Built-in Diode Characteristics



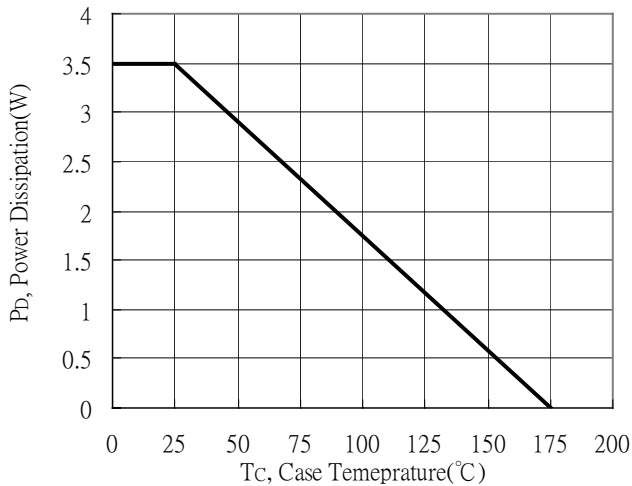
Capacitance vs Reverse-Biased Voltage



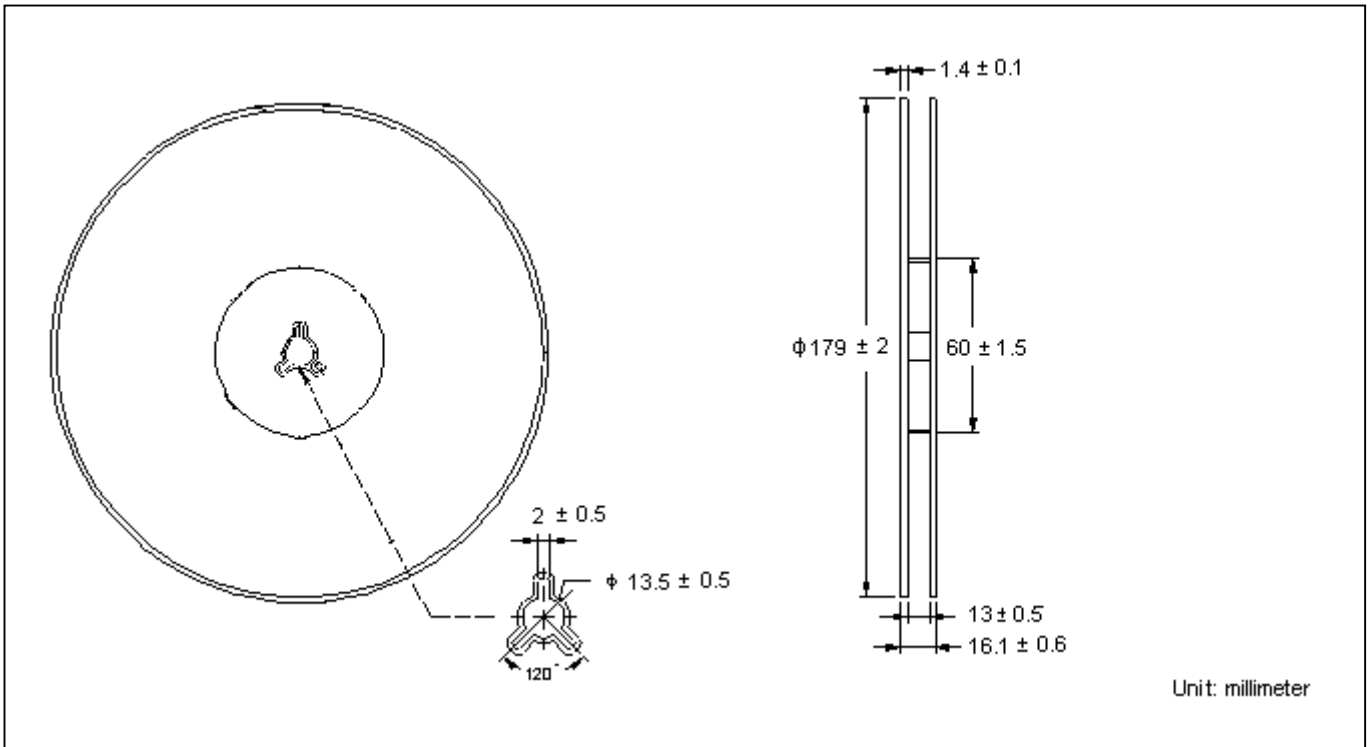
Power Derating Curves



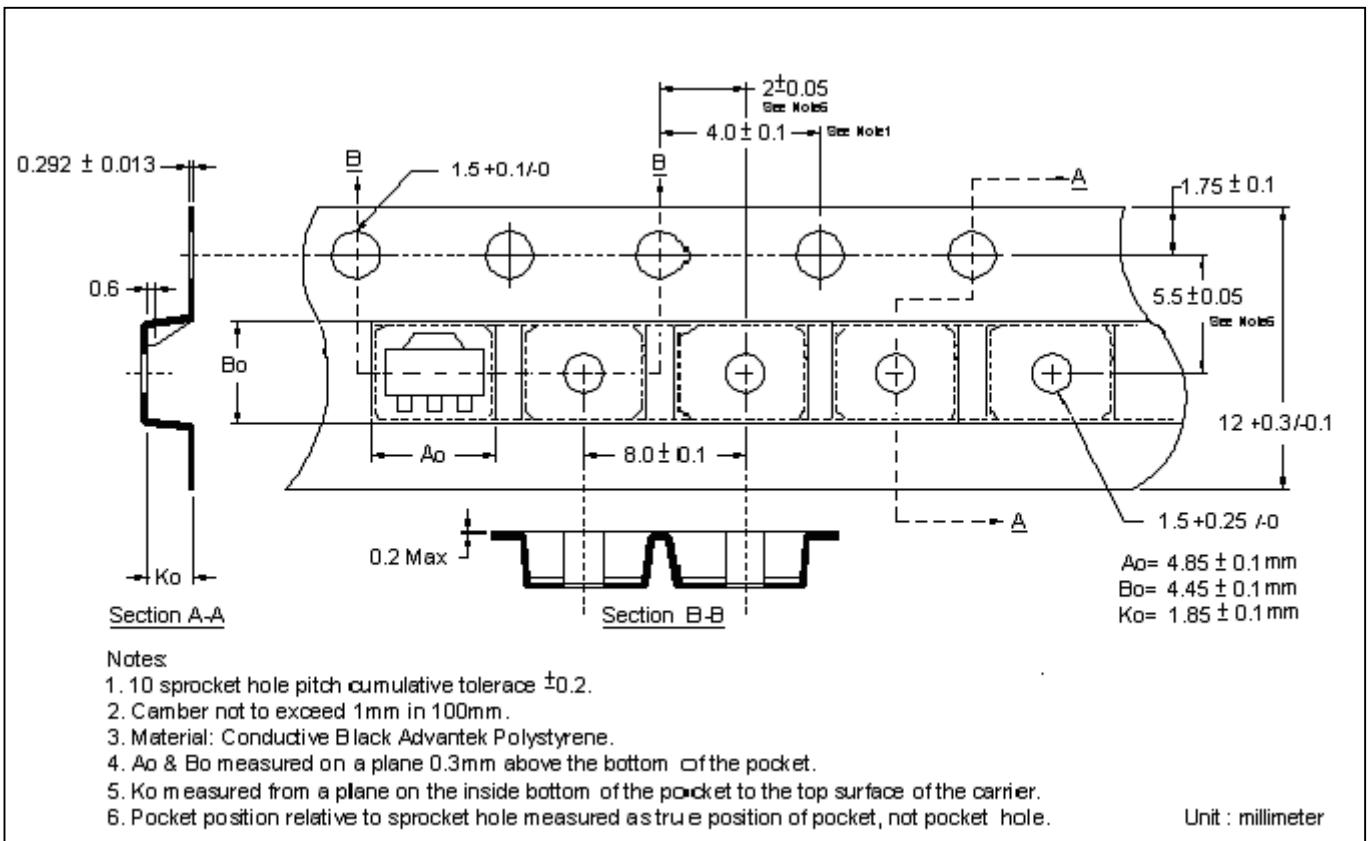
Power Derating Curve



Reel Dimension



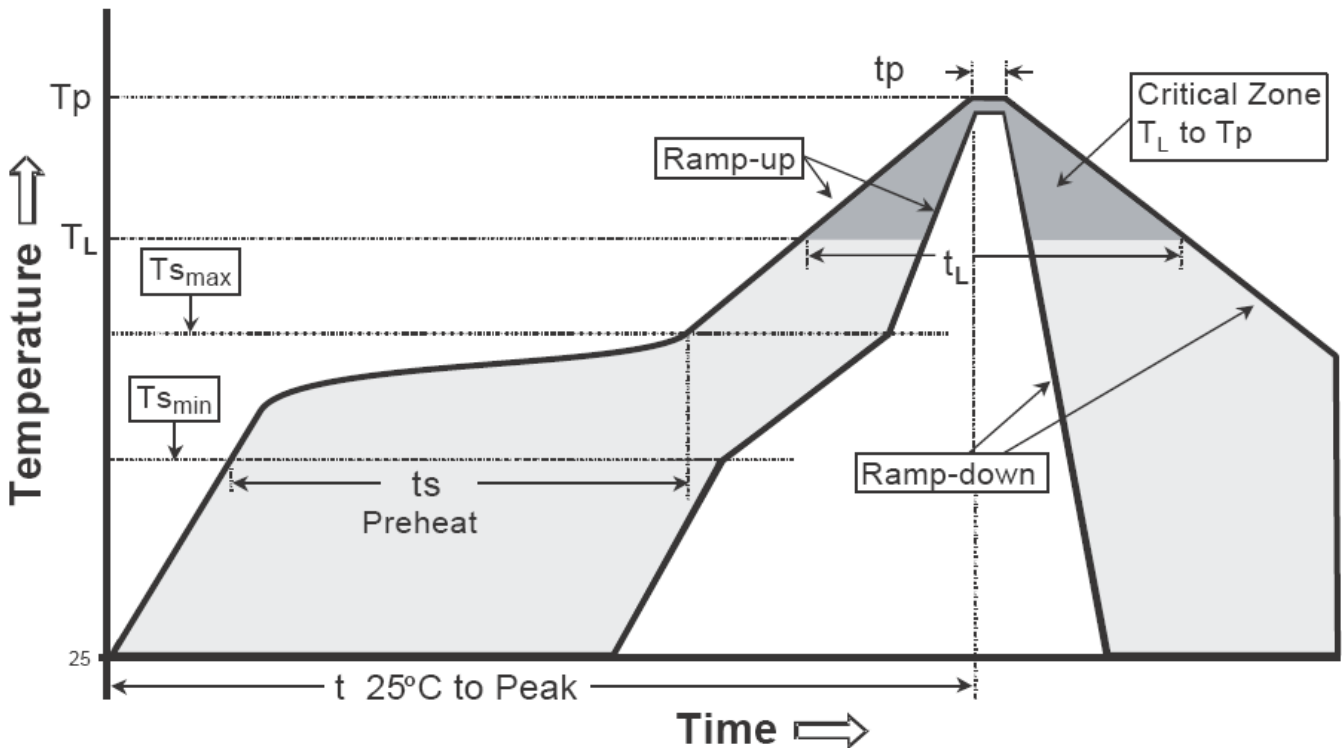
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

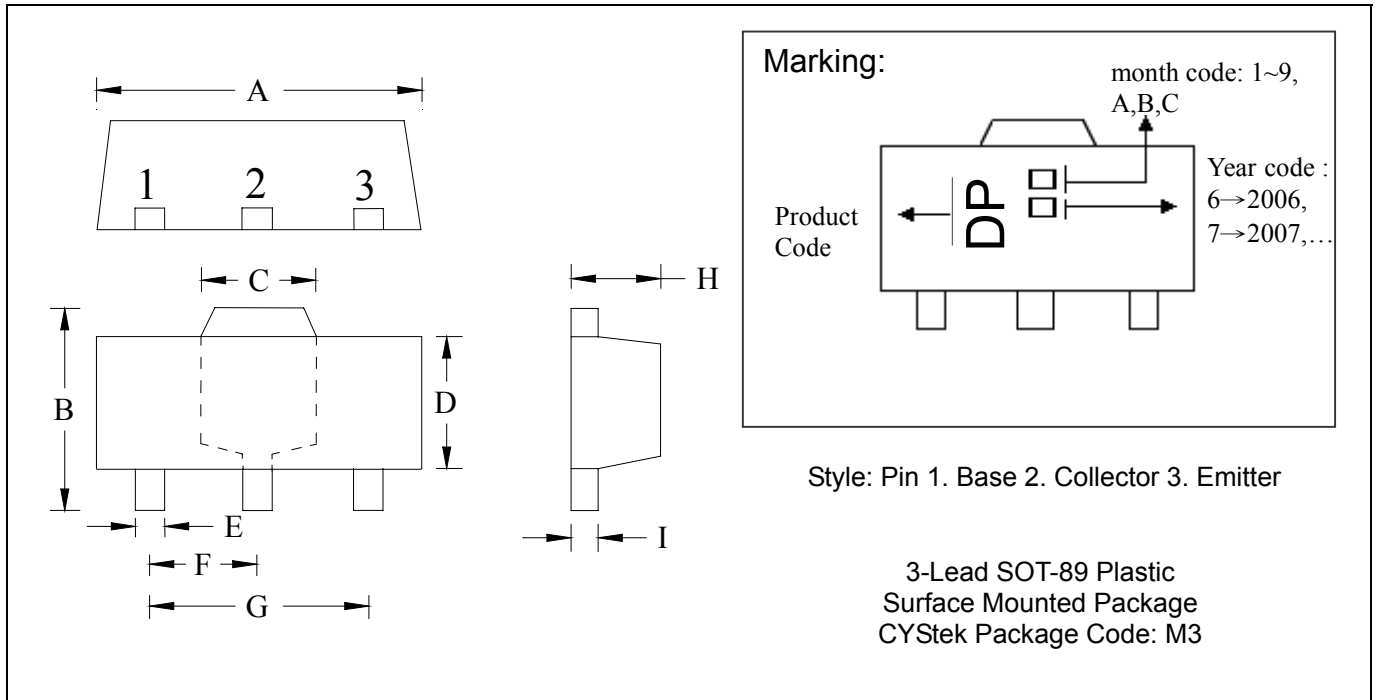
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591	TYP	1.50	TYP
B	0.1551	0.1673	3.94	4.25	G	0.1181	TYP	3.00	TYP
C	0.0610	REF	1.55	REF	H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of CYStek.
- CYStek reserves the right to make changes to its products without notice.
- CYStek **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.